


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32WB55CGU6	70MI*495XXXY	A	998Z	18-09-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	99.55	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7X7X0.55	48	No lead	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	70MI*495XXXY				6000001.0	1000001.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	8.602	mg	supplier	die	Silicon (Si)	7440-21-3		7.941	mg	923157	79770				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	3720	321				
				supplier	metallization	Copper (Cu)	7440-50-8		0.280	mg	32551	2813				
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	116	10				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.091	mg	10579	914				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	349	30				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	233	20				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.071	mg	8254	713				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.181	mg	21042	1818				
				Die Attach Epoxy_EN4900GC_Hitachi	M-011 Other inorganic materials	2.763	mg	Supplier	Organic Compound	Acrylic resin	Proprietary		0.231	mg	83744	2324
Supplier	Organic Compound	Polybutadiene derivative	Proprietary						0.150	mg	54187	1504				
Supplier	Organic Compound	Butadiene copolymer	Proprietary						0.027	mg	9852	273				
Supplier	Organic Compound	Epoxy resin	Proprietary						0.068	mg	24631	684				
Supplier	Organic Compound	Acrylate	Proprietary						0.150	mg	54187	1504				
Supplier	Organic Compound	Peroxide	Proprietary						0.014	mg	4926	137				
Supplier	Organic Compound	Additive	Proprietary						0.027	mg	9852	273				
Supplier	Metals	Silver (Metal powder)	7440-22-4						2.096	mg	758621	21057				
EMC_G770_Sumitomo	M-011 Other inorganic materials	29.924	mg					Supplier	Organic Compound	Epoxy Resin A	Proprietary		0.594	mg	19837	5963
								Supplier	Organic Compound	Epoxy Resin B	Proprietary		0.594	mg	19837	5963
				Supplier	Organic Compound	Phenol Resin A	Proprietary		0.594	mg	19837	5963				
				Supplier	Organic Compound	Phenol Resin B	Proprietary		0.594	mg	19837	5963				
				Supplier	Glass	Silica (Amorphous) A	60676-86-0		21.918	mg	732452	220169				
				Supplier	Glass	Silica (Amorphous) B	7631-86-9		4.871	mg	162767	48926				
				Supplier	Metallic Compound	Metal Hydroxide	Proprietary		0.594	mg	19837	5963				
				Supplier	Additives	Carbon Black	1333-86-4		0.167	mg	5595	1682				
BondingWire_Au_MKE	Bonding Wire	0.690	mg	Supplier	Metals	Gold	7440-57-5		0.690	mg	1000000	6929				
Anode Ball_Tin_Asahi	Metals	3.693	mg	Supplier	Metals	Tin	7440-31-5		3.693	mg	1000000	37094				
Leadframe_C7+Ag_HDS	Metals	53.878	mg	Supplier	Metals	Nickel	7440-02-0		1.582	mg	29365	15893				
				Supplier	Glass	Silicon	7440-21-3		0.350	mg	6500	3518				
				Supplier	Metals	Magnesium	7439-95-4		0.084	mg	1565	847				
				Supplier	Metals	Silver	7440-22-4		3.394	mg	63000	34097				
				Supplier	Metals	Copper	7440-50-8		48.467	mg	899570	486865				